10

chamber.

## **CLAIM AMENDMENTS**

Please amend the claims as described below. In accordance with 37 CFR §1.121, a complete listing of all claims in the application is provided below. Notably, the status of each claim is indicated in the parenthetical expression adjacent to the corresponding claim number.

Claims 1-35 (Canceled).

- 1 36. (Previously Presented) An electromechanical device comprising: 2 a substrate; 3 a mechanical structure disposed over the substrate wherein a monolayer or selfassembled layer is disposed on at least a portion of the mechanical structure; 4 5 a film encapsulation structure, disposed over the mechanical structure, to define and 6 seal a chamber; 7 an anti-stiction channel, etched into the film encapsulation structure, to provide 8 access to at least a portion of the mechanical structure disposed in the chamber; and 9 an anti-stiction plug, disposed over or in the anti-stiction channel, to re-seal the
- 37. (Previously Presented) The device of claim 36 wherein the film encapsulation
   structure includes first and second encapsulation layers.
- 1 38. (Currently Amended) The device of claim 37 wherein the first encapsulation
  2 layer <u>includes</u> is comprised of polycrystalline silicon, porous polycrystalline silicon,

- 3 amorphous silicon, silicon carbide, silicon nitride, silicon/germanium, germanium, or gallium
- 4 arsenide.
- 1 39. (Currently Amended) The device of claim 37 wherein the second
- 2 encapsulation layer includes is comprised of polycrystalline silicon, porous polycrystalline
- 3 silicon, amorphous silicon, germanium, silicon/germanium, gallium arsenide, or silicon
- 4 carbide.
- 1 40. (Previously Presented) The device of claim 36 wherein the anti-stiction plug
- 2 includes spin-on polymer, SOG or a metal material.
- 1 41. (Previously Presented) The device of claim 36 wherein the anti-stiction plug
- 2 includes spin-on polymer or SOG which is deposited using silk screening.
- 1 42. (Previously Presented) The device of claim 36 wherein the anti-stiction plug
- 2 includes spin-on polymer or SOG which is deposited using dispensed seal-glass, plastic
- 3 and/or epoxy.
- 1 43. (Previously Presented) The device of claim 36 wherein the anti-stiction plug is
- 2 deposited using a shadow mask technology.
- 1 44. (Previously Presented) The device of claim 36 further including a trap,
- 2 disposed between the anti-stiction channel and the mechanical structure.

- 1 45. (Previously Presented) The device of claim 44 wherein the trap is a
- 2 substantially vertical trap.
- 1 46. (Previously Presented) The device of claim 44 wherein the trap is a
- 2 substantially horizontal trap.
- 1 47. (Currently Amended) The device of claim 36 35 further including a diffusion
- 2 barrier disposed over the anti-stiction plug.
- 1 48. (Currently Amended) The device of claim 47 wherein the diffusion barrier
- 2 includes is comprised of a metal material.
- 1 49. (Previously Presented) An electromechanical device comprising:
- 2 a substrate:
- 3 a mechanical structure disposed over the substrate wherein a monolayer or self-
- 4 assembled layer is disposed on at least a portion of the mechanical structure;
- 5 a wafer bonded encapsulation structure, disposed over the mechanical structure, to
- 6 define and seal a chamber;
- 7 an anti-stiction channel, etched into the substrate, to provide access to at least a
- 8 portion of the mechanical structure disposed in the chamber; and
- 9 an anti-stiction plug, disposed over or in the anti-stiction channel, to re-seal the
- 10 chamber.

- 50. (Previously Presented) The device of claim 49 wherein the encapsulation 1
- 2 structure is secured over the mechanical structure using anodic bonding.
- 1 51. (Previously Presented) The device of claim 49 wherein the encapsulation
- 2 structure includes an anodic shield.

6509688102

- 1 52. (Previously Presented) The device of claim 49 wherein the encapsulation
- 2 structure includes an insulation layer which is disposed on a cap wafer.
- 53. (Previously Presented) The device of claim 49 wherein the anodic shield is 1
- 2 disposed on the insulation layer.
- 1 54. (Previously Presented) The device of claim 49 wherein the anti-stiction plug
- 2 includes spin-on polymer, SOG or a metal material.
- 1 55. (Previously Presented) The device of claim 49 wherein the anti-stiction plug
- 2 includes spin-on polymer or SOG which is deposited using silk screening.
- 1 56. (Previously Presented) The device of claim 49 wherein the anti-stiction plug
- 2 includes spin-on polymer or SOG which is deposited using dispensed seal-glass, plastic
- 3 and/or epoxy.

- 57. (**Previously Presented**) The device of claim 49 wherein the anti-stiction plug is deposited using a shadow mask technology.
- 1 58. (Previously Presented) The device of claim 49 further including a trap, 2 disposed between the anti-stiction channel and the mechanical structure.
- 1 59. (**Previously Presented**) The device of claim 58 wherein the trap is a 2 substantially vertical trap.
- 1 60. (Previously Presented) The device of claim 58 wherein the trap is a 2 substantially horizontal trap.
- 1 61. (**Previously Presented**) The device of claim 49 further including a diffusion 2 barrier disposed over the anti-stiction plug.
- 62. (Currently Amended) The device of claim 61 wherein the diffusion barrier
   includes is comprised of a metal material.
- 1 63. (NEW) An electromechanical device comprising:
- 2 a substrate;
- a mechanical structure disposed over the substrate wherein an anti-stiction layer is
   disposed on at least a portion of the mechanical structure;

a film encapsulation structure, disposed over the mechanical structure, to define a chamber:

STEINBERG

- 7 an anti-stiction channel, formed in the film encapsulation structure, to allow the anti-
- 8 stiction layer to be disposed on at least the portion of the mechanical structure disposed in
- 9 the chamber; and
- an anti-stiction plug, disposed over or in the anti-stiction channel, to re-seal the
- 11 chamber,
- 1 64. (NEW) The device of claim 63 wherein the film encapsulation structure
- 2 includes first and second encapsulation layers.
- 1 65. (NEW) The device of claim 64 wherein the first encapsulation layer includes
- 2 polycrystalline silicon, porous polycrystalline silicon, amorphous silicon, silicon carbide,
- 3 silicon nitride, silicon/germanium, germanium, or gallium arsenide.
- 1 66. (NEW) The device of claim 64 wherein the second encapsulation layer
- 2 includes polycrystalline silicon, porous polycrystalline silicon, amorphous silicon,
- 3 germanium, silicon/germanium, gallium arsenide, or silicon carbide.
- 1 67. (NEW) The device of claim 63 wherein the anti-stiction plug includes spin-on
- 2 polymer, SOG or a metal material.

- 1 68. (NEW) The device of claim 63 wherein the anti-stiction plug includes spin-on
- 2 polymer or SOG which is deposited using silk screening.
- 1 69. (NEW) The device of claim 63 wherein the anti-stiction plug includes spin-on
- 2 polymer or SOG which is deposited using dispensed seal-glass, plastic and/or epoxy.
- 1 70. (NEW) The device of claim 63 wherein the anti-stiction plug is deposited using
- 2 a shadow mask technology.
- 1 71. (NEW) The device of claim 63 further including a trap, disposed between the
- 2 anti-stiction channel and the mechanical structure.
- 1 72. (NEW) The device of claim 71 wherein the trap is a substantially vertical trap.
- 1 73. (NEW) The device of claim 71 wherein the trap is a substantially horizontal
- 2 trap.
- 1 74. (NEW) The device of claim 71 wherein the trap includes a substantially
- 2 horizontal portion and a substantially vertical portion.
- 1 75. (NEW) The device of claim 63 further including a diffusion barrier disposed
- 2 over the anti-stiction plug.

- 1 76. (NEW) The device of claim 75 wherein the diffusion barrier is a metal layer.
- 1 77. (NEW) The device of claim 63 wherein the anti-stiction layer is a monolayer or
- 2 self-assembled layer.